

IN THE CLAIMS:

Please amend claim 1 as indicated below:

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1. (Amended) A semiconductor light emitting device comprising at least one semiconductor light emitting element of edge-emission type, a first heat sink and a second heat sink, wherein at least a part of an electrode for a first-conduction-type semiconductor of the semiconductor light emitting element is in contact with the first heat sink; at least a part of an electrode for a second-conduction-type semiconductor of the semiconductor light emitting element is in contact with the second heat sink; and the first heat sink and the second heat sink are in contact with each other in a junction overlooking one of the two side planes which do not compose facets of a cavity in the semiconductor light emitting element.

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6. (Amended) The semiconductor light emitting device as claimed in Claim 1, wherein a space (B) is provided in the vicinity of the junction of the first heat sink (11) and the second heat sink (12), into which an adhesive (15b) used for joining the first heat sink (11) and the second heat sink (12) can flow to thereby prevent the adhesive (15b) from reaching the semiconductor light emitting element (4).